

Figure 1a

Wet Bench: oxide etch + hydrophilic clean (RCA clean)

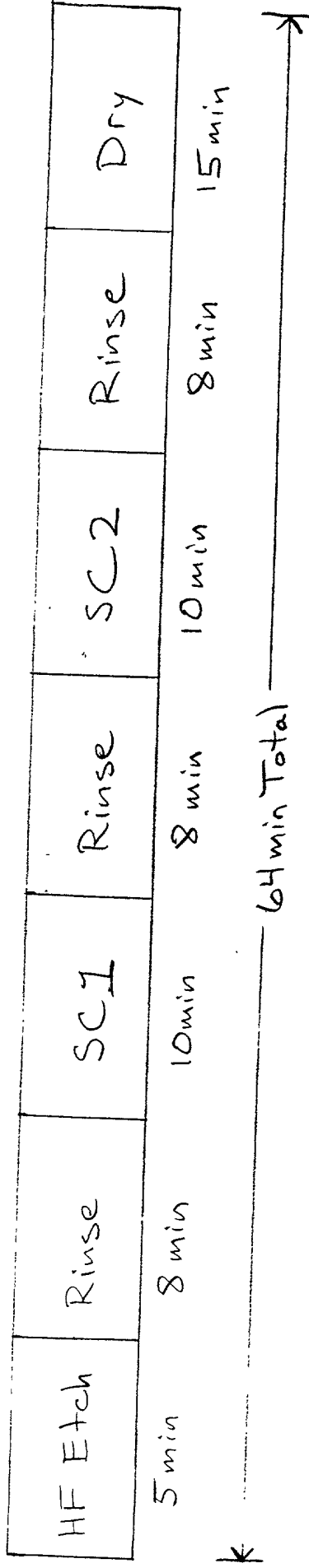


Figure 1b

Single Wafer Cleaning Tool Single Step Clean
oxide etch + hydrophilic clean

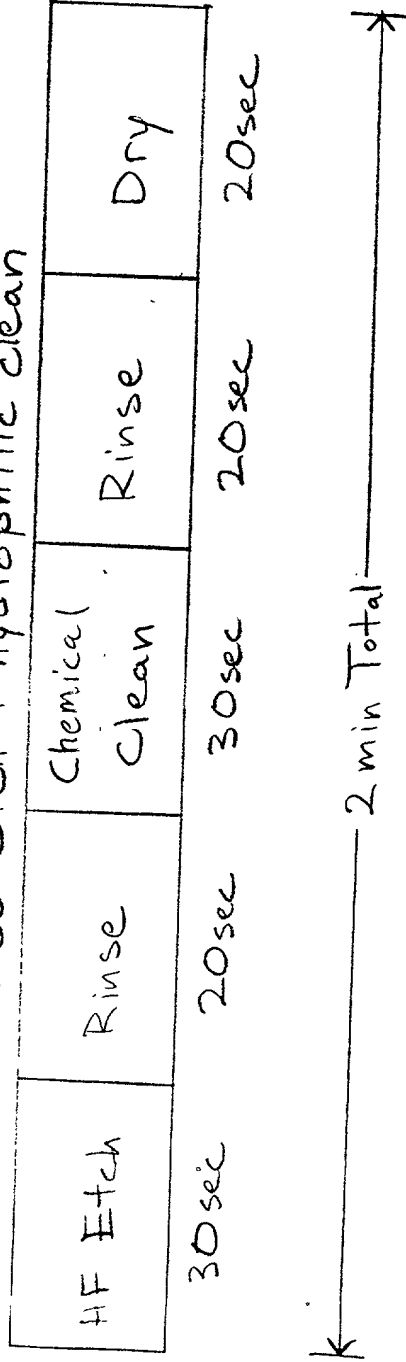
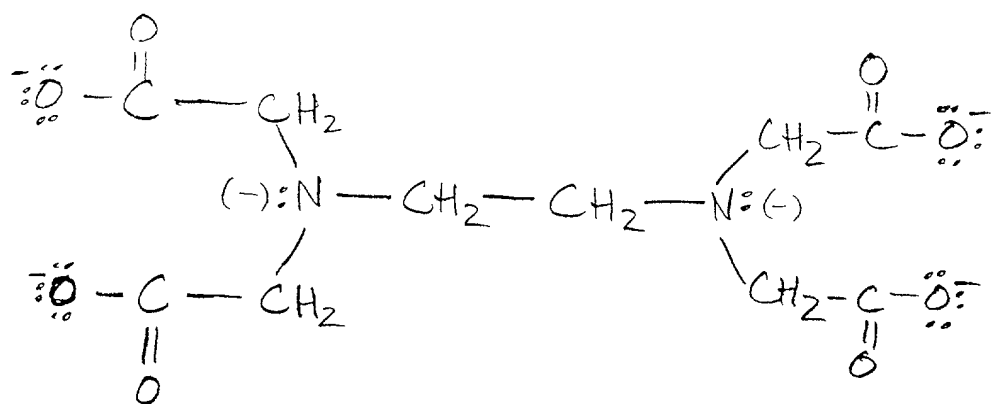
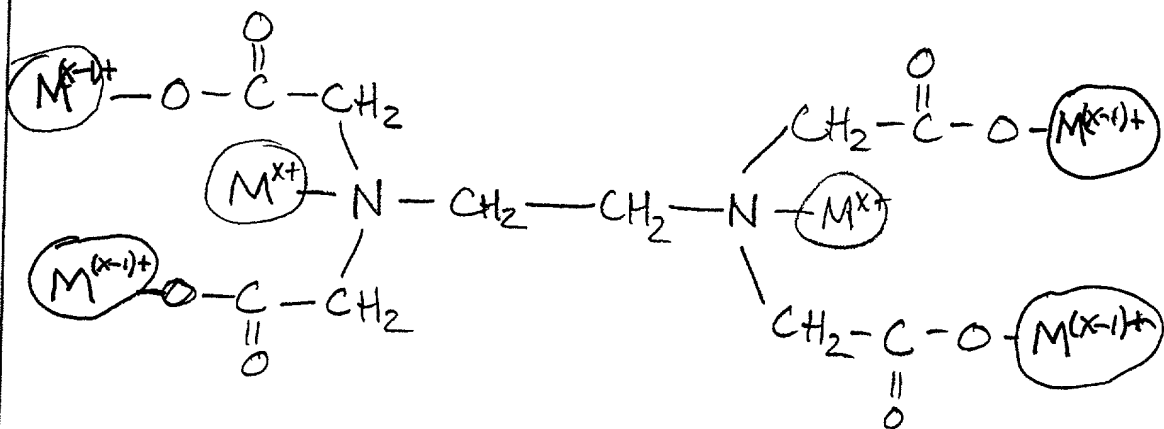


Figure 2 a



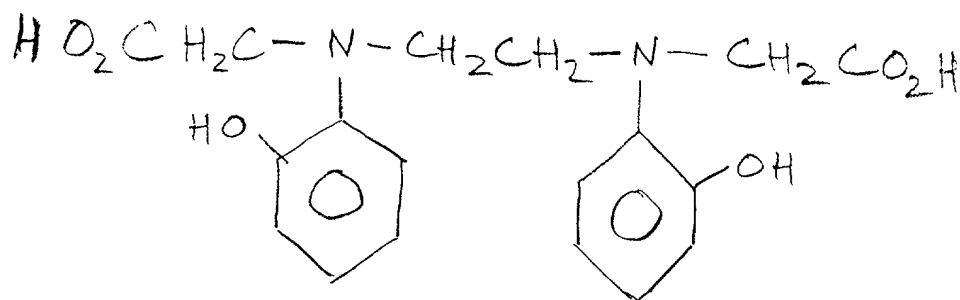
↓ Binds Metal ions

Figure 2b



(HPED)

Figure 3a



(TTTA)

Figure 3b

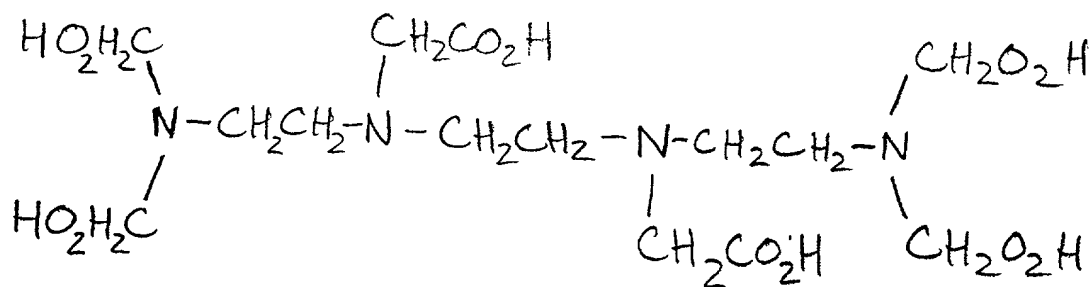
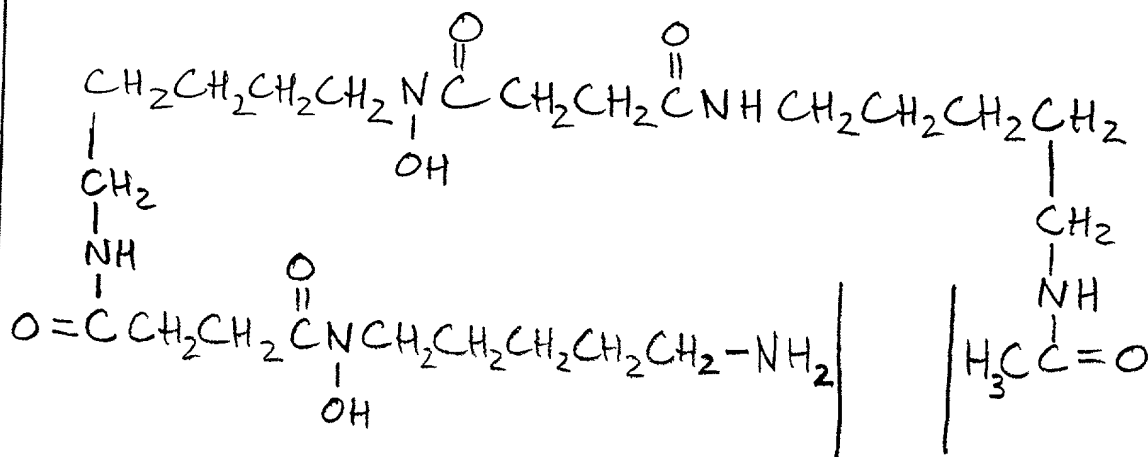


Figure 3c

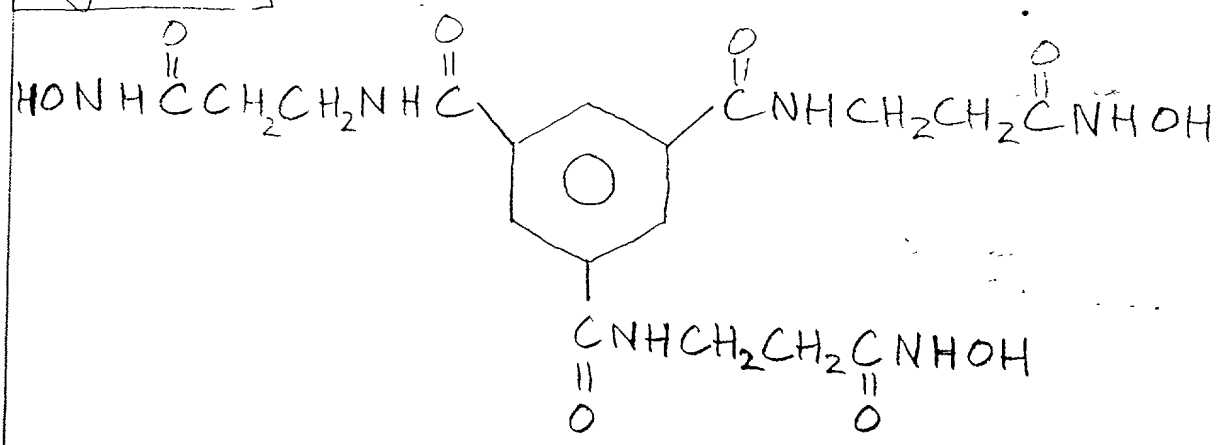
DesferriFerrioxamin B



T03350-062T6850

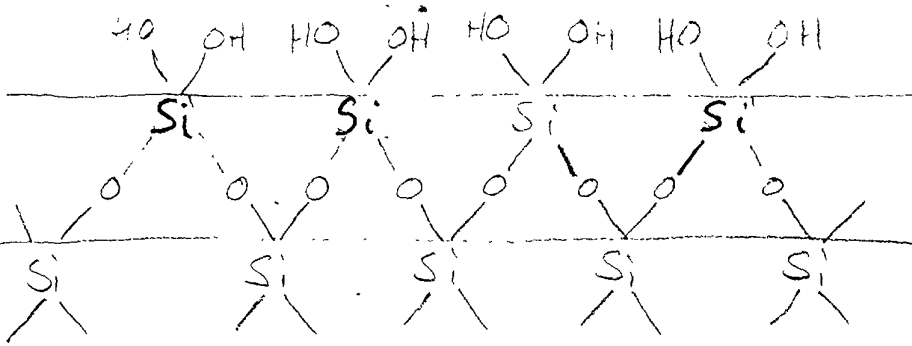
BAMFPH

Figure 3.d



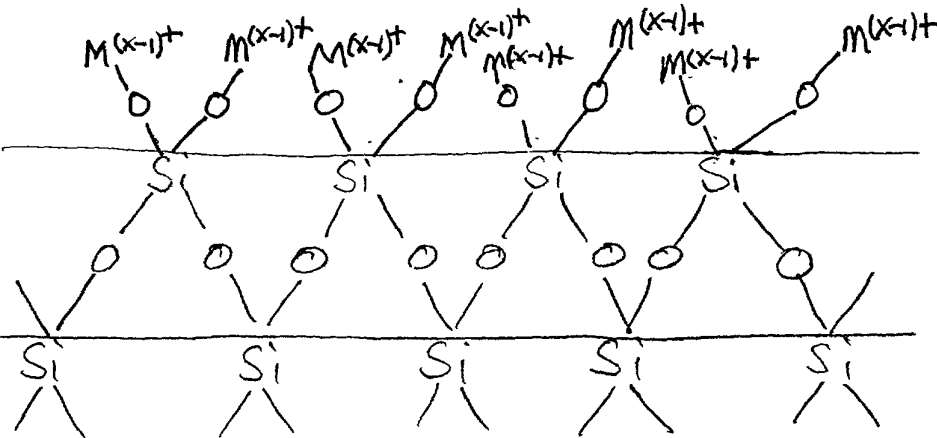
TO 350 OF 1550

Figure 4 a



Hydroxide
terminated
 SiO_2 film

Figure 4 b



Chemisorption

090130-06501
10000-067650

Fig. 5

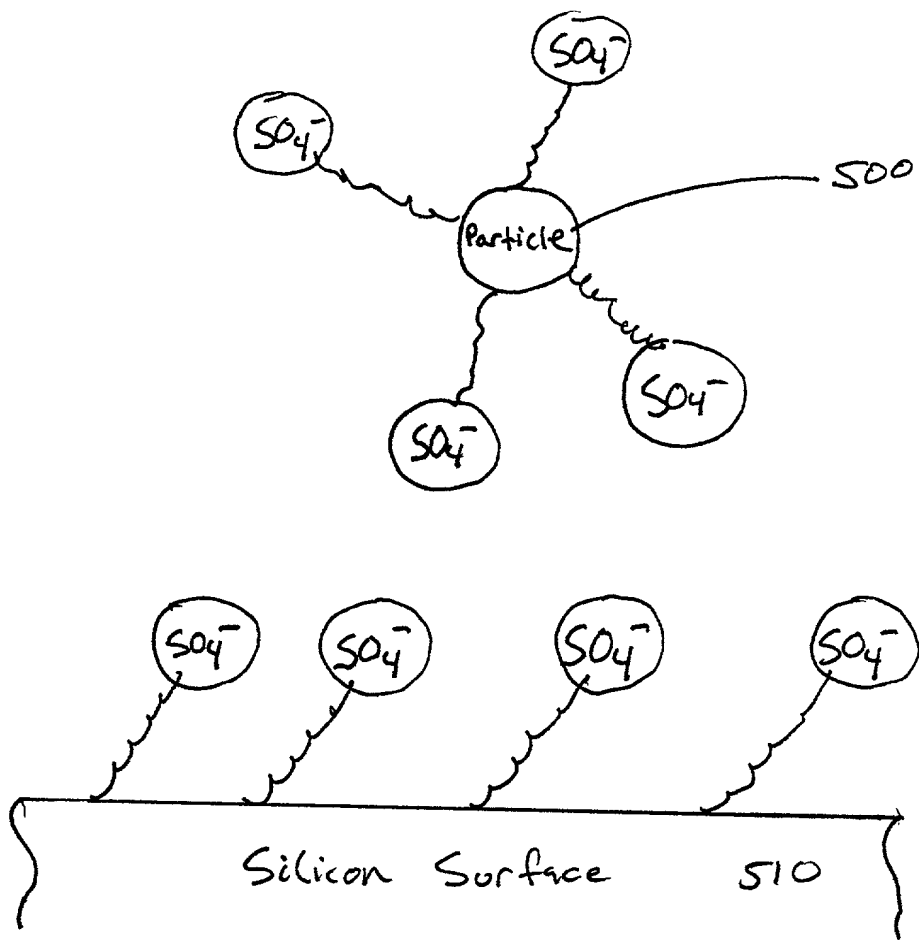


Figure 6a

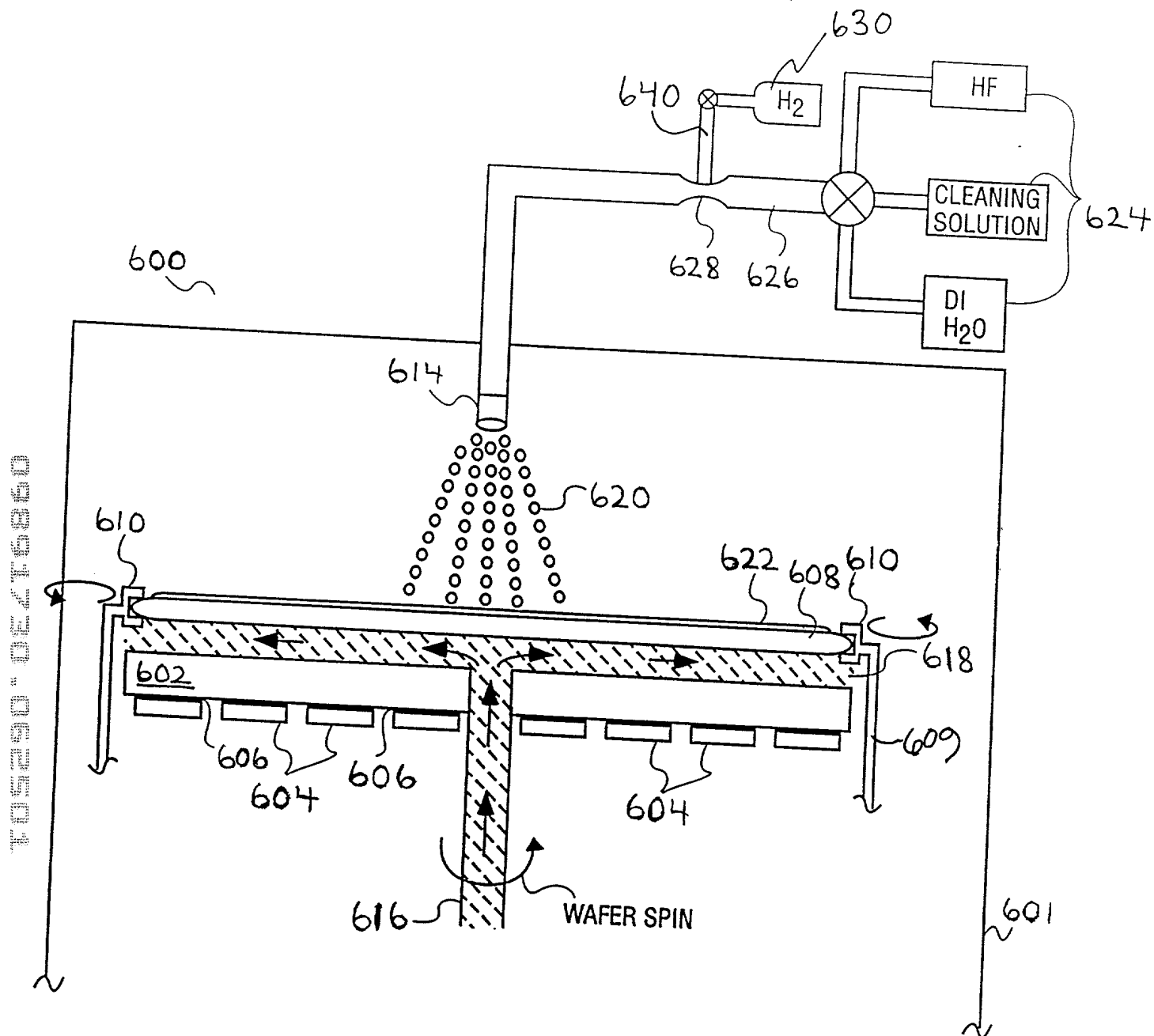


Figure 6b

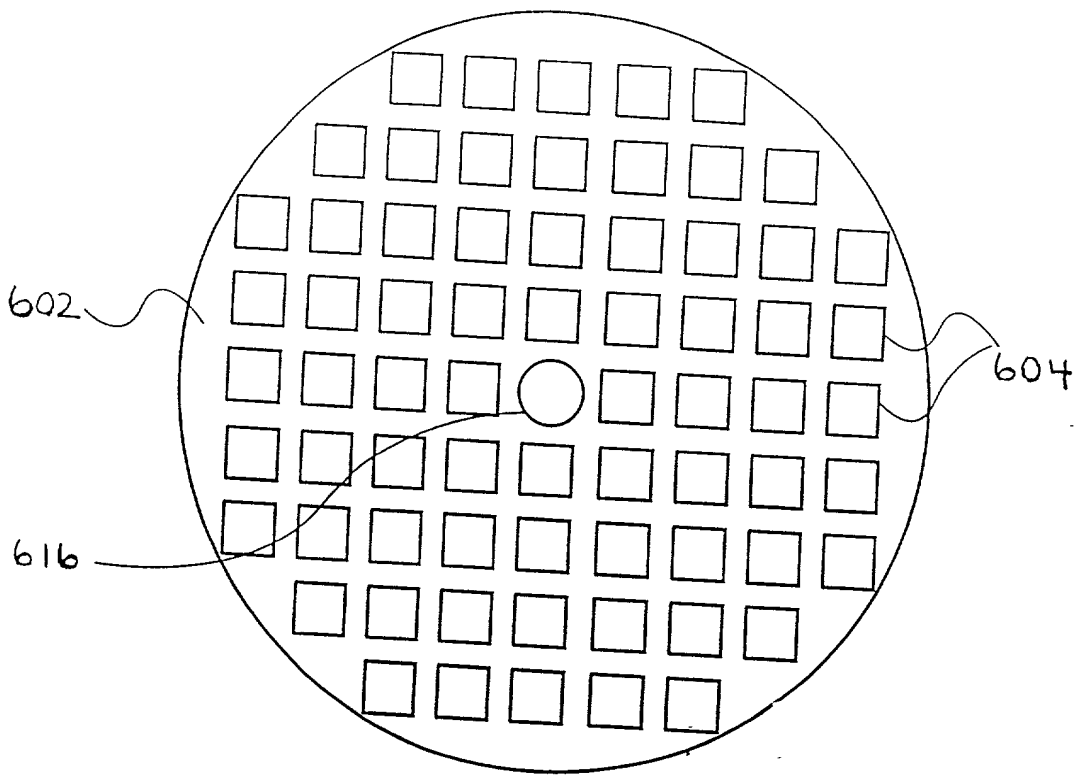


Figure 6c

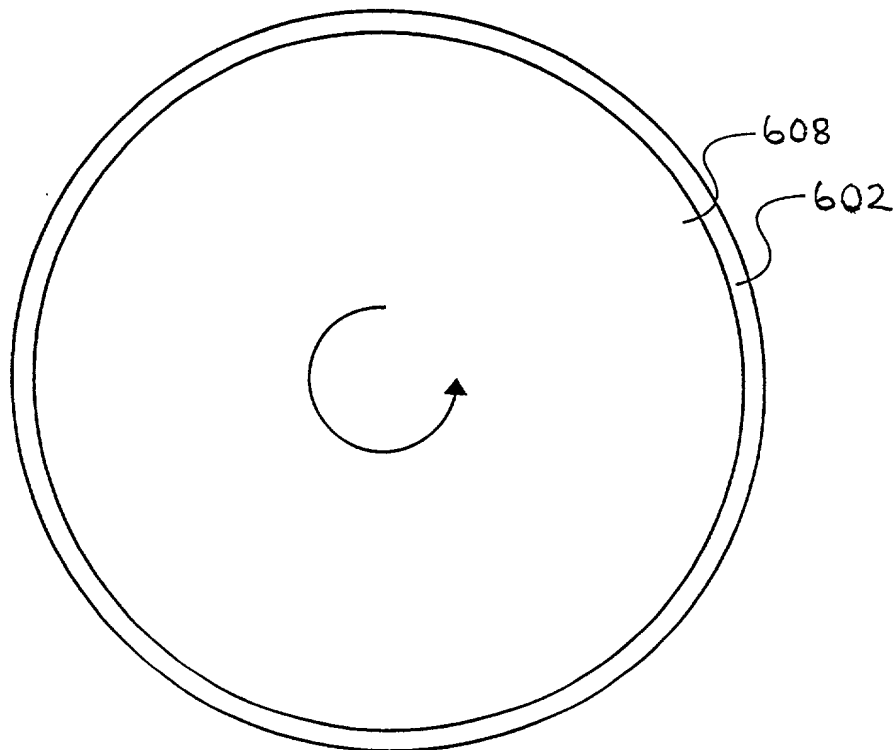
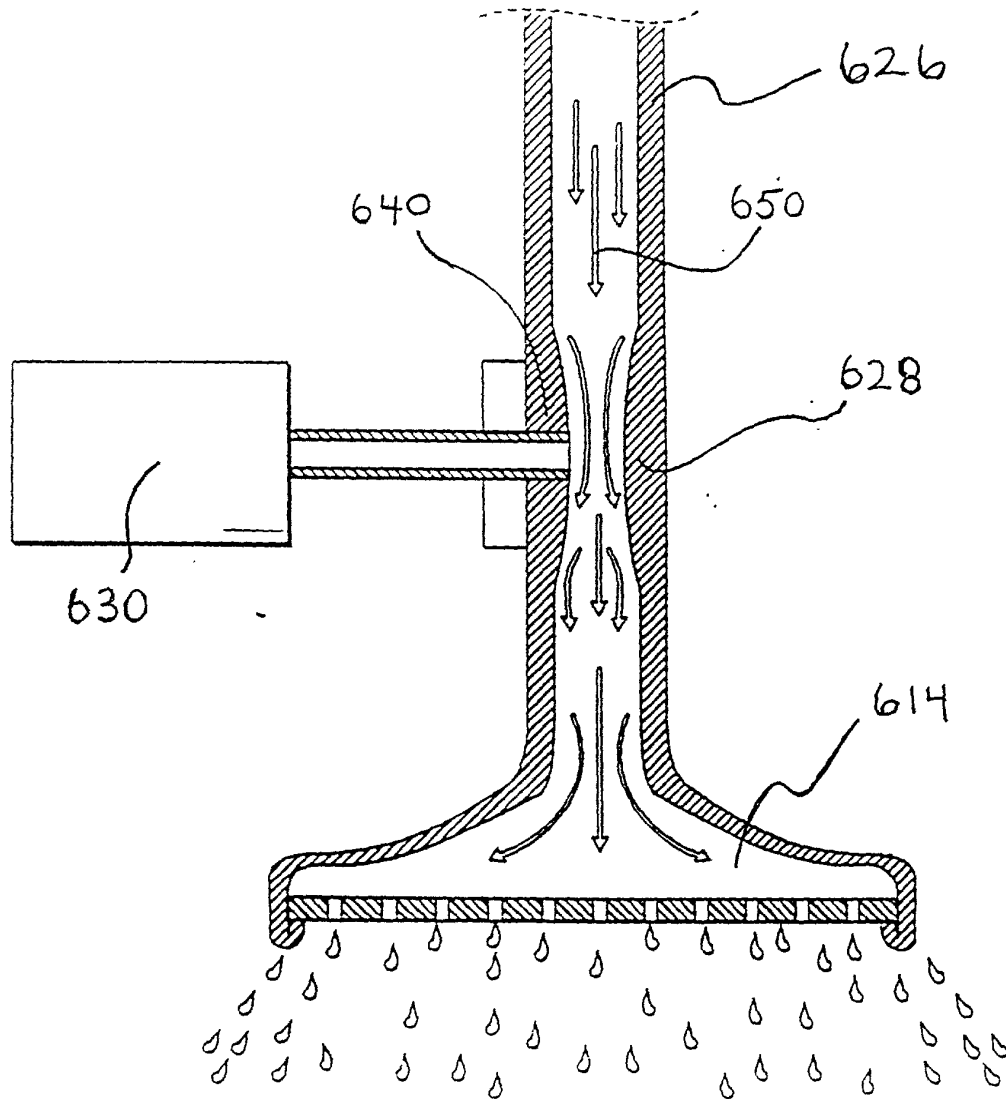


Figure 6d



TOP SECRET

FIGURE 7a

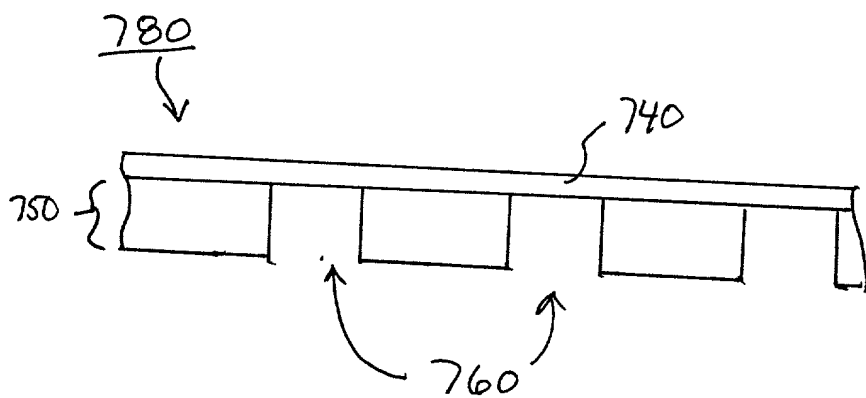
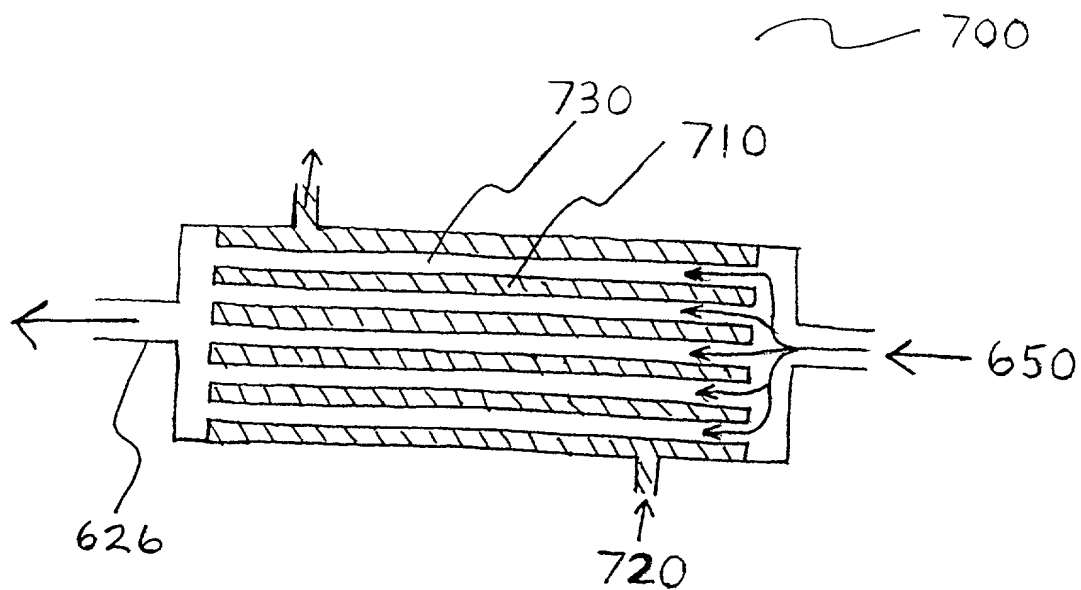


Fig. 7b

Figure 7c

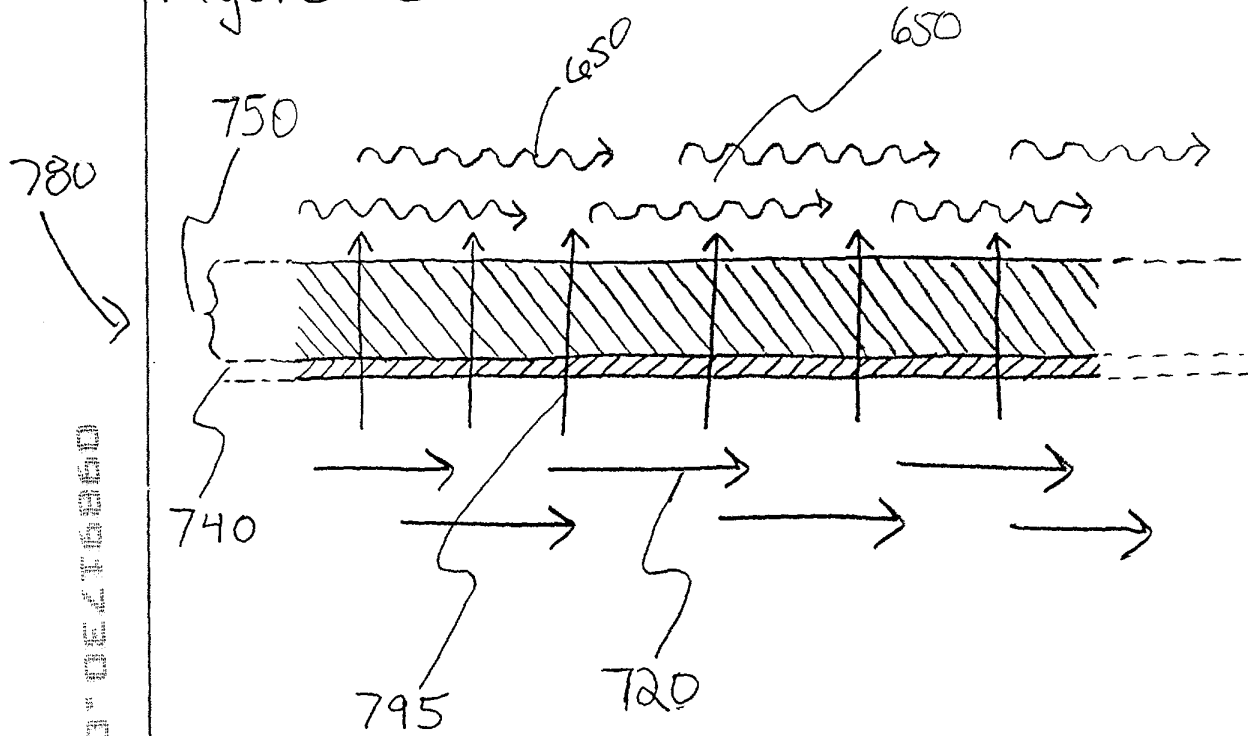


Fig. 8

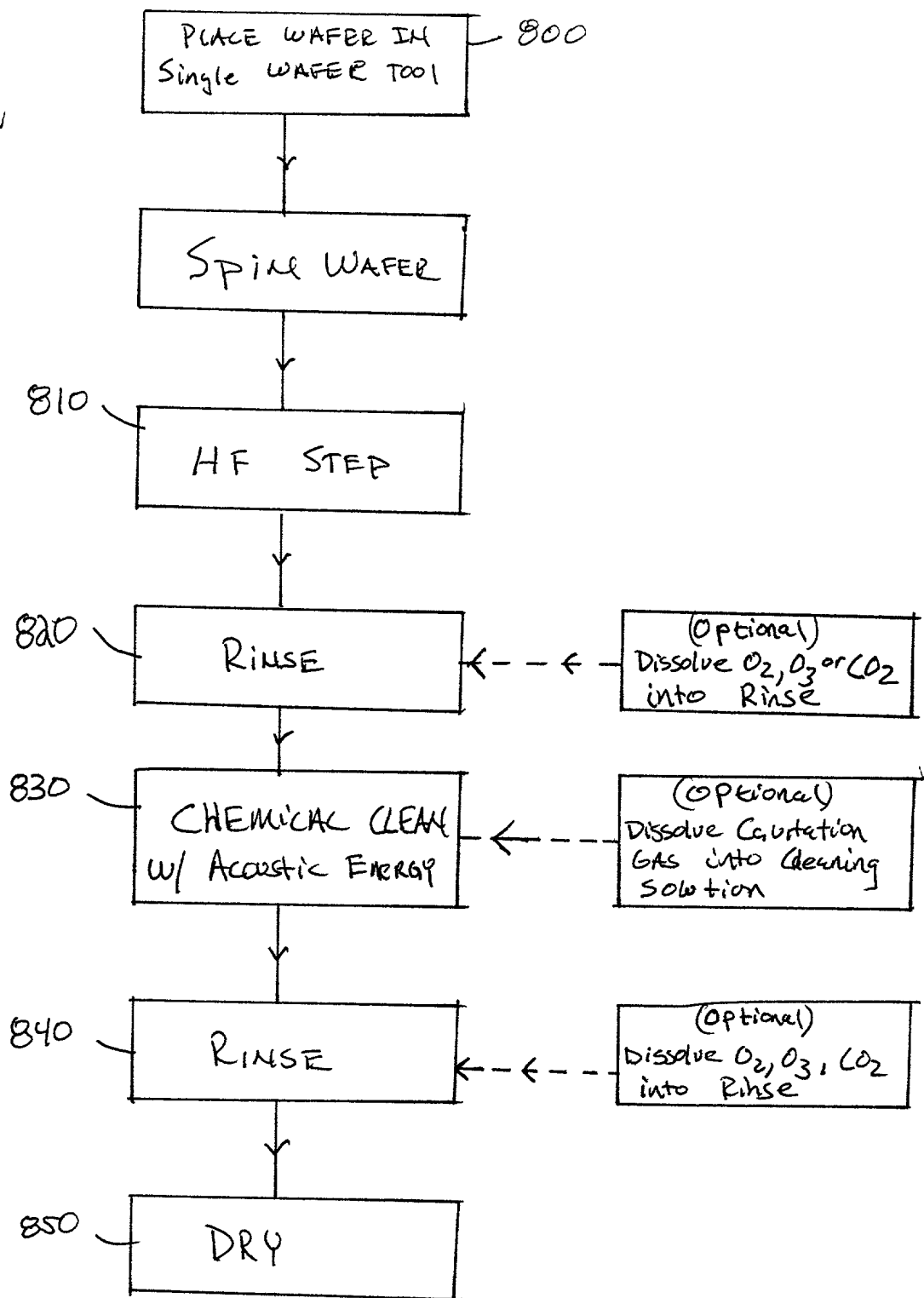
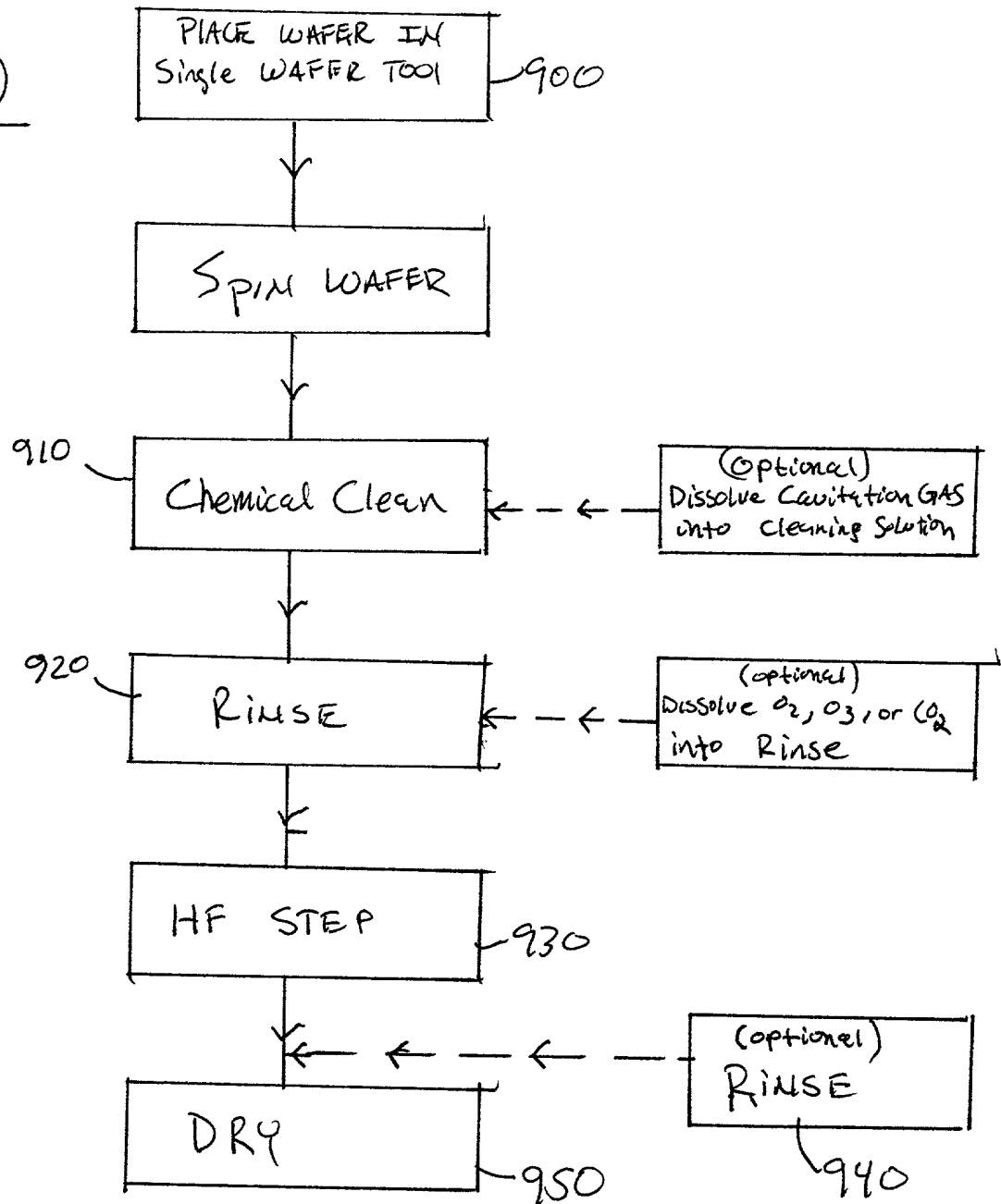


Fig. 9

[illegible]

HF etch diagram

Figure 10a

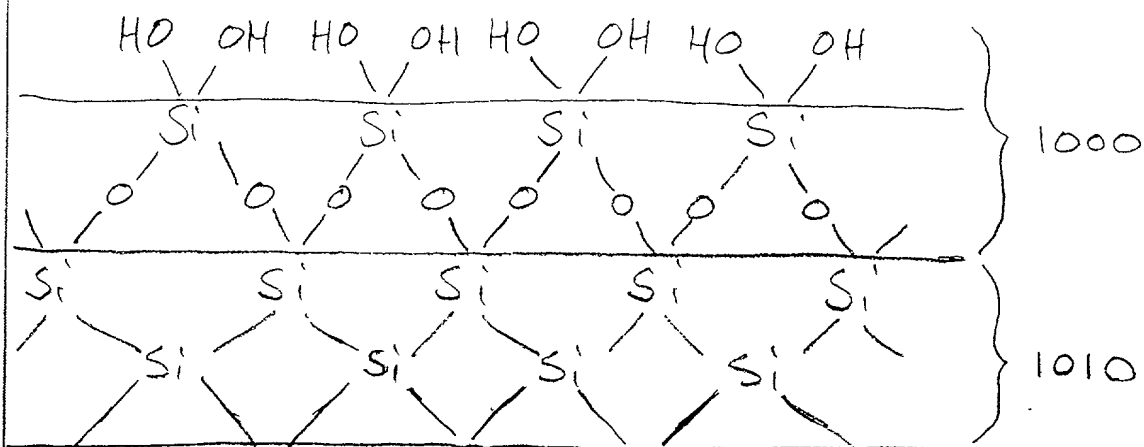


Figure 10b Hydrophobic Surface

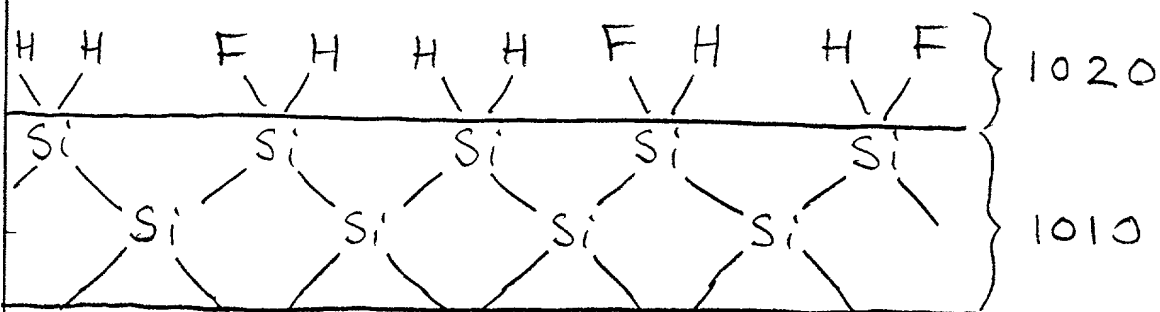


Fig 11

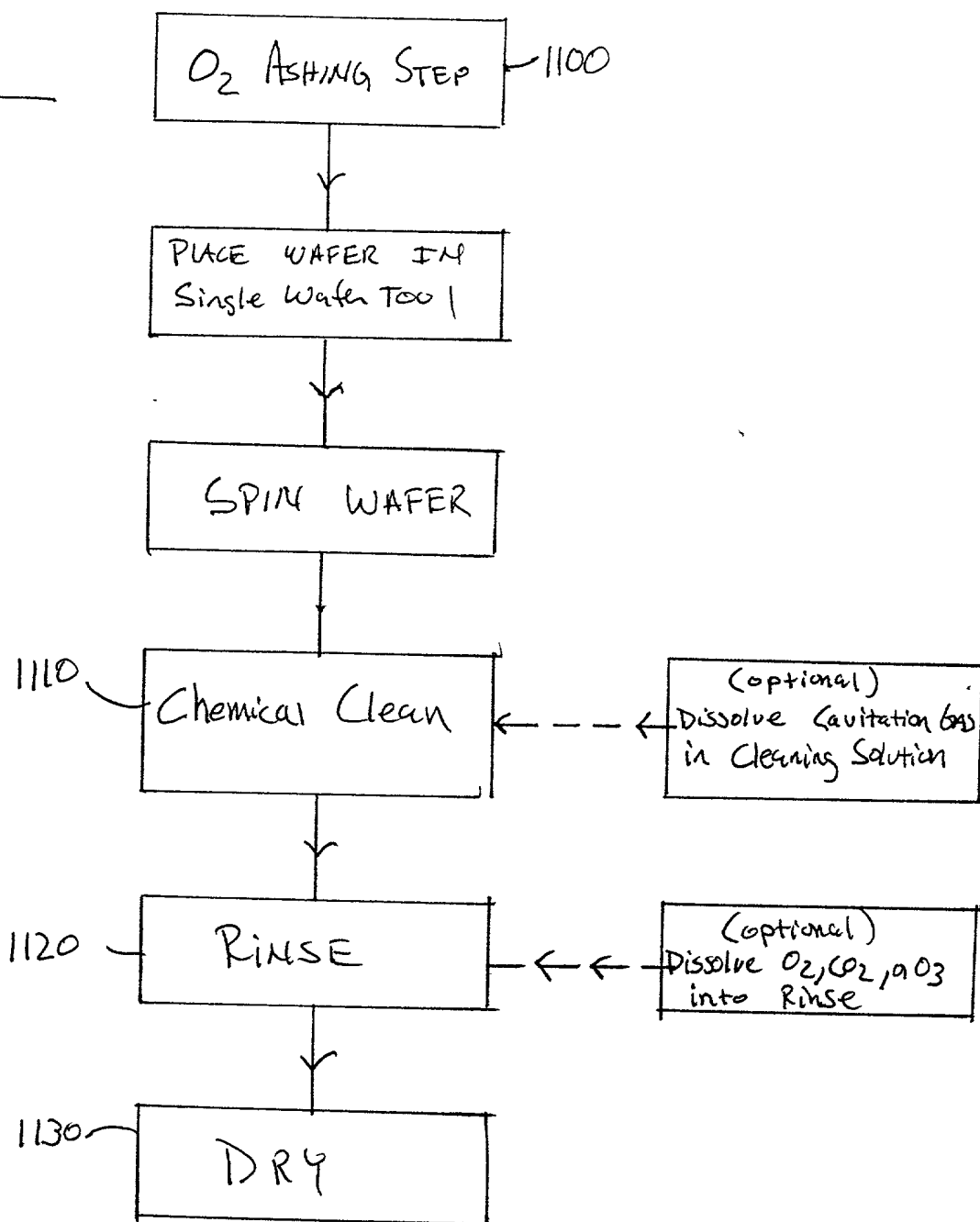


Fig. 12

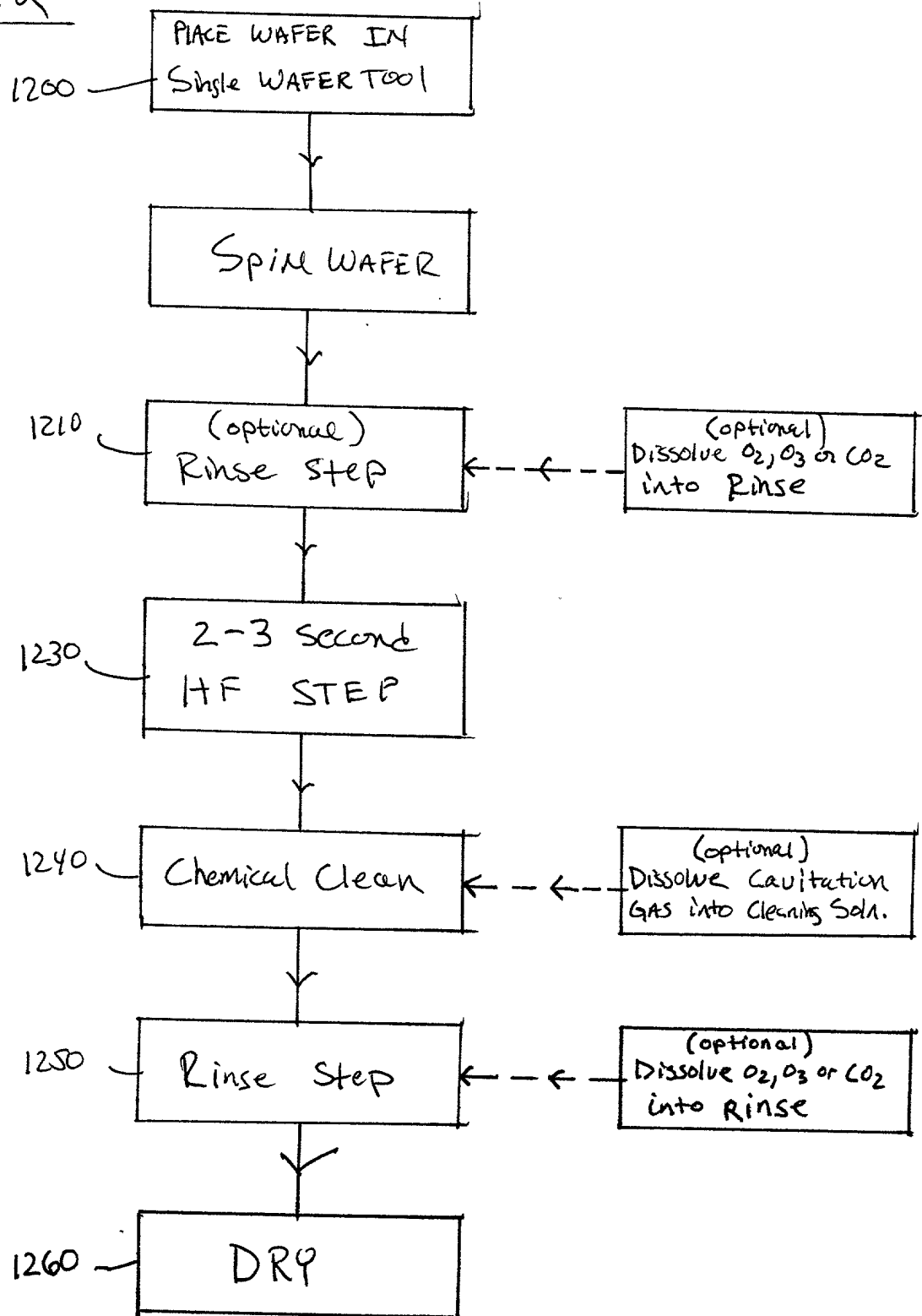


FIG. 12 OF 16

Figure 13a

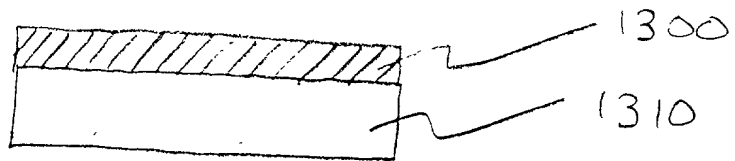


Figure 13b

